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| APPLICATION NO. | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. |
|----------------------------------|-------------|----------------------|---------------------|------------------|
| 10/816,227 | 04/01/2004 | Yoshikatsu Imazeki | 9319S-000707 | 7313 |
| 27572 | 7590 | 01/20/2006 | EXAMINER | |
| HARNESS, DICKEY & PIERCE, P.L.C. | | | CHIU, TSZ K | |
| P.O. BOX 828 | | | ART UNIT | |
| BLOOMFIELD HILLS, MI 48303 | | | PAPER NUMBER | |
| | | | 2822 | |

DATE MAILED: 01/20/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

| | | | |
|------------------------------|-------------------------------|--------------------------------|--|
| Office Action Summary | Application No. 10/816,227 | Applicant(s) IMAZEKI ET AL. | |
| | Examiner Tsz K. Chiu | Art Unit 2822 | |

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 01 April 2004.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-11 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-11 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413) Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date <u>7/26/05</u> . | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Response to Arguments

Applicant's election with traverse of species I, claims 1-11 that was filed on October 24, 2005 is acknowledged. Applicant elects Group I, claim 1-11 drawn to a electro-optical device with traverse. The applicant argues that there would be no serious burden in the examining both groups. However, Group I is drawn to a electro-optical device and Group II is drawn to method of electro-optical device. The inventions Group I and Group II are related as process of making and product made and the invention Group II and I belong to different classes, which require separate searches and considerations. The separate searches and considerations for each group would provide a burden on the examiner. As such, the restriction is proper and the restriction is final. It is suggested that non-elected claims 12-13 be canceled in the response to this Office Action.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

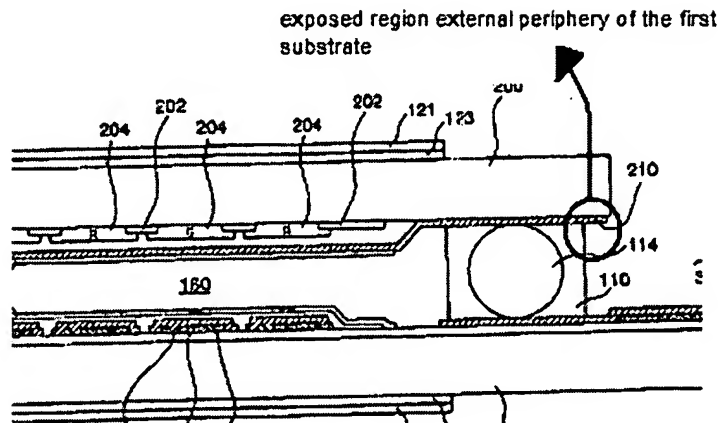
Claim 1-11 rejected under 35 U.S.C. 102(b) as being anticipated by Hanakawa et al. (USPUB 2002/0005928).

With respect to claim 1 and 5, Hanakawa discloses in Fig. 2 a first substrate (200); a protection layer (205) formed on the first substrate (200) leaving a region of the

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first substrate exposed (right side of 200); a first electrode (left side of 210) formed on the protection layer (205); a first inter-substrate conduction unit formed (210) on the protection layer (205) and electrically connected to the first electrode (left side of 210); a second substrate (300) opposing the first substrate (200) and having a second electrode (350) formed thereon; a second inter-substrate conduction unit (left side of 350 below conductive particle 114) formed on the second substrate and electrically connected to the second electrode (350); a first wiring pattern (210) formed on the first substrate (200) and electrically connected to the first inter-substrate conduction unit (210); a metallic wiring pattern formed at a lower layer of the protection layer (205) and electrically connected to the first wiring pattern (210); a conductive member (114) interposed between the first inter-substrate conduction unit (210) and the second inter-substrate conduction unit (left side of 350 below conductive particle 114), to electrically connect both units together; and a sealant (110) that contains the conductive member bonding the first substrate (200) and the second substrate (300) together by extending on the protection layer (205) and the exposed region (left side of the 110 region not for on first electrode) of the first substrate (200) where the protection layer (205) is not formed.

With respect to claim 2 and 8, Hanakawa discloses the exposed region of the first substrate extends inboard from an external periphery of the first substrate (see drawing below).



With respect to claim 3 and 9, Hanakawa discloses a shape of the protection layer (205, For example Fig. 2) disposed at a bottom of the first inter-substrate conduction unit (210) is coordinated with a shape of the first inter-substrate conduction unit (210).

With respect to claim 4, Hanakawa discloses a color filter (204, For example Fig. 2) is formed at a lower layer of the protection layer (205, For example Fig. 2) disposed on the first substrate (200, For example Fig. 2); and the first substrate (200, For example Fig. 2) is larger than the second substrate (300, For example Fig. 2) so that an extended region of the first substrate (200, For example Fig. 2) produced when both the substrates (200,300, For example Fig. 2) are bonded together is provided with a mounting terminal to be connected to the first inter-substrate conduction unit (210, For example Fig. 2).

With respect to claim 6, Hanakawa discloses a material of the first wiring pattern. (210) is the same as a material of the first inter-substrate conduction unit (210); and a resistance of the metallic wiring pattern (312) is smaller than a resistance of the first wiring pattern (210).

With respect to claim 7, Hanakawa discloses the metallic wiring pattern comprises any one of silver, a silver alloy, aluminum, and an aluminum alloy (page 1, paragraph 10).

With respect to claim 10, Hanakawa discloses in Fig. 2 a first substrate (200); a protection layer (205) formed on the first substrate (200) leaving a region of the first substrate exposed (right side of 200); a first electrode (left side of 210) formed on the protection layer (205); a first inter-substrate conduction unit formed (210) on the protection layer (205) and electrically connected to the first electrode (left side of 210); a second substrate (300) opposing the first substrate (200) and having a second electrode (350) formed thereon; a second inter-substrate conduction unit (left side of 350 below conductive particle 114) formed on the second substrate and electrically connected to the second electrode (350); a first wiring pattern (210) formed on the first substrate (200) and electrically connected to the first inter-substrate conduction unit (210); a metallic wiring pattern formed at a lower layer of the protection layer (205) and electrically connected to the first wiring pattern (210); a conductive member (114) interposed between the first inter-substrate conduction unit (210) and the second inter-substrate conduction unit (left side of 350 below conductive particle 114), to electrically connect both units together; and a sealant (110) having a region that contains the conductive member (114) and a region with a thickness larger than that of the region for embracing the conductive member (114) so as to bond the first substrate (200) and the second substrate (300) together.

With respect to claim 11, Hanakawa discloses an electronic instrument (page 1, paragraph 1) comprising an electro-optical device according to claim 1.

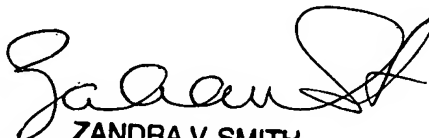
Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tsz K. Chiu whose telephone number is 517-272-8656. The examiner can normally be reached on 0800 to 1700.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra V. Smith can be reached on 571-272-2429. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

TKC
November 10, 2005

SUPERVISORY PATENT EXAMINER
ZANDRA V. SMITH


ZANDRA V. SMITH
SUPERVISORY PATENT EXAMINER
1/19/2006